

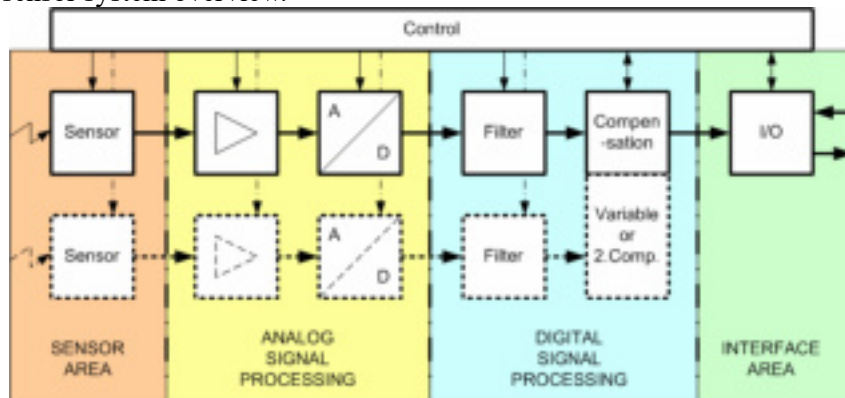
SystemC-AMS Modeling at Infineon Technologies Austria – AIM SC

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Automotive, Industrial and Multimarket, Sense and Control,
Infineon Technologies Austria AG, Villach, AUSTRIA,
wolfgang.granig@infineon.com, wolfgang.scherr@infineon.com

AUTOMOTIVE SENSOR SYSTEMS:

The requirements for modeling automotive sensors systems are shown on hand of a general automotive sensor system overview.

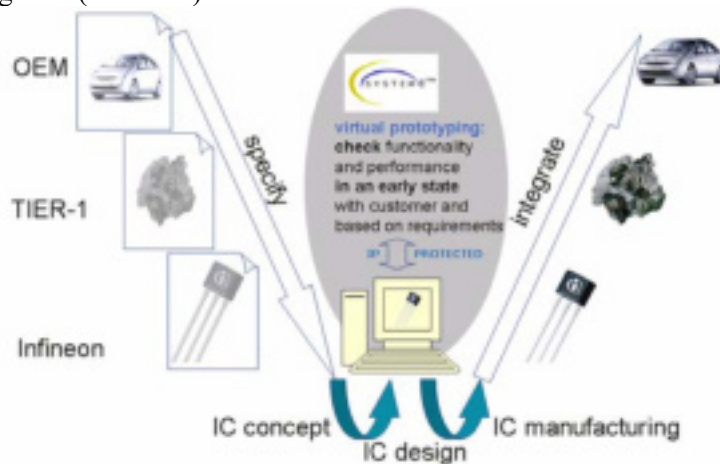


The requirements and solutions for modeling the physical behavior of capacitive/resistive/Hall/GMR or Inertia Sensor-cells are shown.

Modeling requirements of the analog signal path comprising ADCs and DACs of different conversion technologies like Switched Capacitor (SC) or Continuous Time (CT) with feedback loops are given.

Modeling of the digital signal processing for hardware-filters and for a configurable inhouse DSP called “Intelligent State Machine (ISM)” is presented as well as modeling of different interfaces used in Automotive Systems.

Also an overview of the information flow beginning at the customer down to the implementation will be given. (V-Model)



As summary all the requirements with their up to now used solutions and possible improvements will be given.

SystemC-AMS Modeling of Embedded Sensors for Automotive Applications

Infineon Technologies Austria AG
Automotive Industrial and Multimarket
Sense & Control

Wolfgang Scherr, Wolfgang Granig
26.June 2007



Never stop thinking

Who I am (Wolfgang Scherr)

- Diploma thesis "A Configurable Controller Core for Embedded-SoC Applications in Sensor-ASICs."
- Working since 1996 for the Siemens Design Center Villach
 - >6 years design experience (also before IFX with part-time jobs)
 - Responsibilities for Communication and Automotive groups:
 - M/S verification
 - M/S simulation methodology in Villach as overall project leader
 - SPICE and Modelsim expert; Author of in-house Modelsim+SPICE coupling
 - design expertise for m/s systems, including embedded processors
- Since 2001 working at Automotive Sense & Control
 - >5 years sensor system experience
 - Concept/System engineer of sensor products (magnetics/pressure)
 - Interests and responsibilities:
 - system modeling methods and prototyping within AIM (SC)
 - still interest in design methodology
 - sensor ASIPs and specific firmware development flows
 - embedded HW architectures, C compilers, HW-a/HW-d/SW partitioning
 - Head of concept engineering group at Sense & Control, Villach
 - Member of OSCI SystemC-AMS working group

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General Requirements

Pressure Sensors

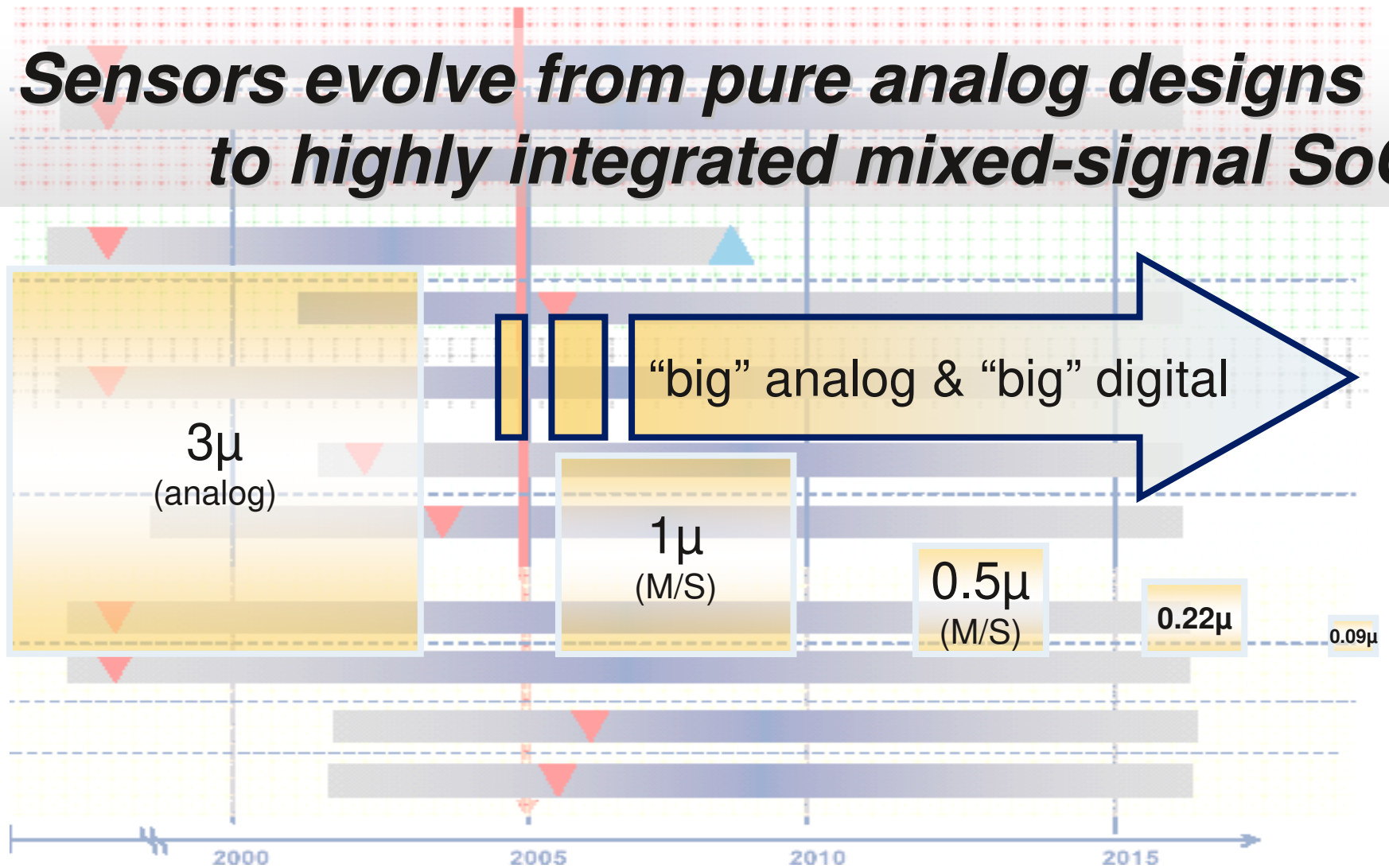
Linear Hall Sensors

GMR Angle Sensors

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- General Requirements**
- Pressure Sensors
- Linear Hall Sensors
- GMR Angle Sensors

Sensors evolve from pure analog designs to highly integrated mixed-signal SoCs



Sensor Products developed at IFX in Villach



Example 1

Powertrain

Safety

Body and
non automotive

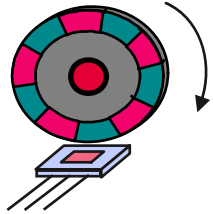
Integrated
Pressure

MAP: KP110/115
BAP: KP120/125

Side Air Bag: KP100
KP105
KP107



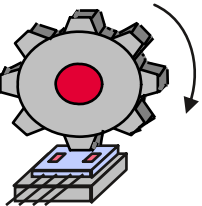
Integrated
Pressure



Differential
Hall

Crank: TLE4925
Cam: TLE4980
Gear Tooth:
TLE4923, TLE4921, TLE4953

Wheel Speed:
TLE4941/42/47



TLE49x5
TLE49x6

Hall
Switches



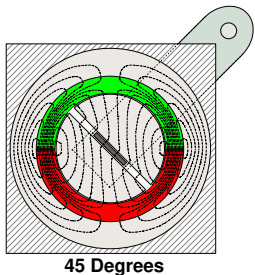
Low Power:
TLE4913/17

Linear
Hall

Pedal, Throttle Pos.,
Industrial, I-Sense:
TLE4990, TLE4997,
TLE4998

Angle sensor:
TLE5010
TLE5011
Wheel speed:
TLE5044

Integrated GMR

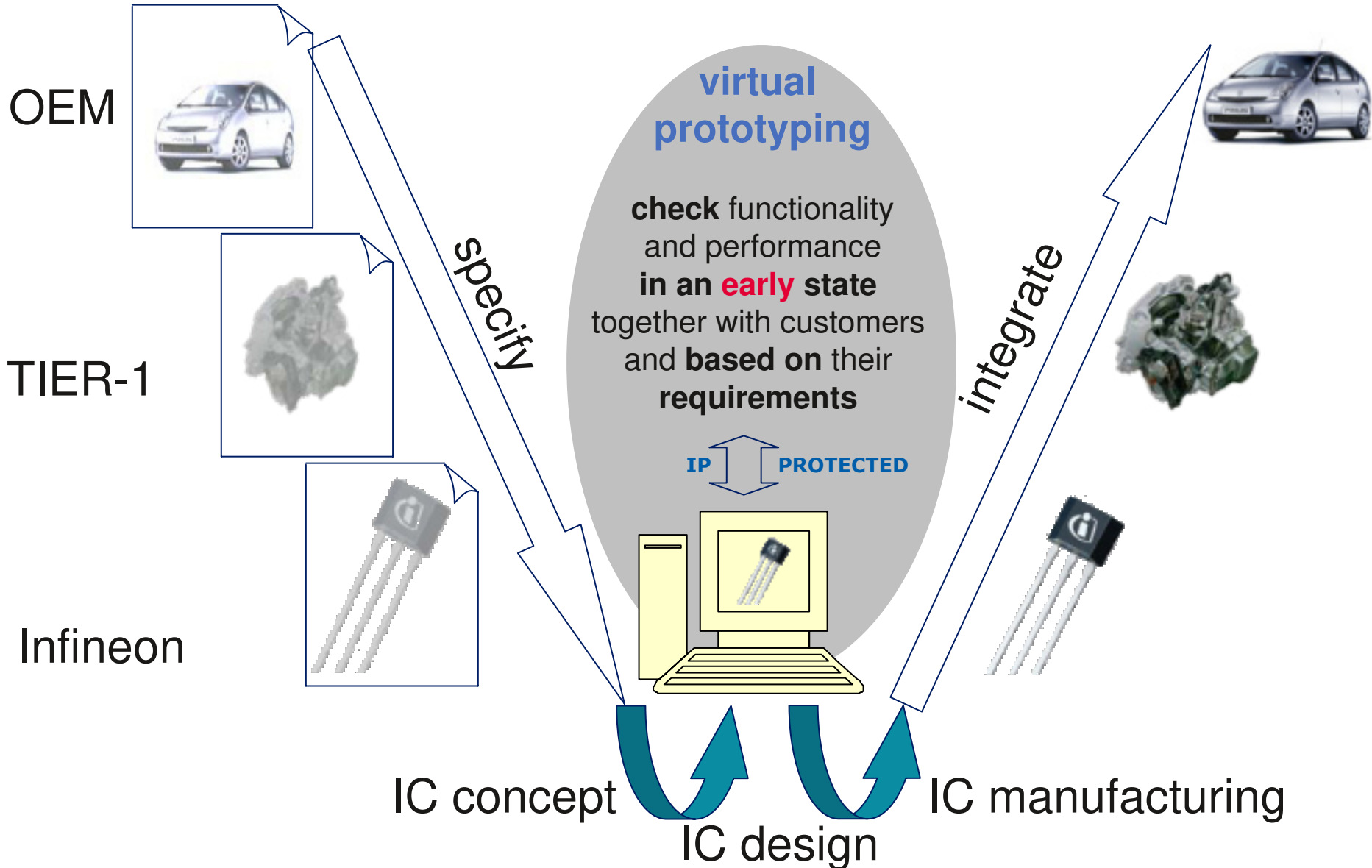


45 Degrees

Example 2

Example 3

Driving a standard for virtual system modeling, get rid of long „loops“ in the development cycle!



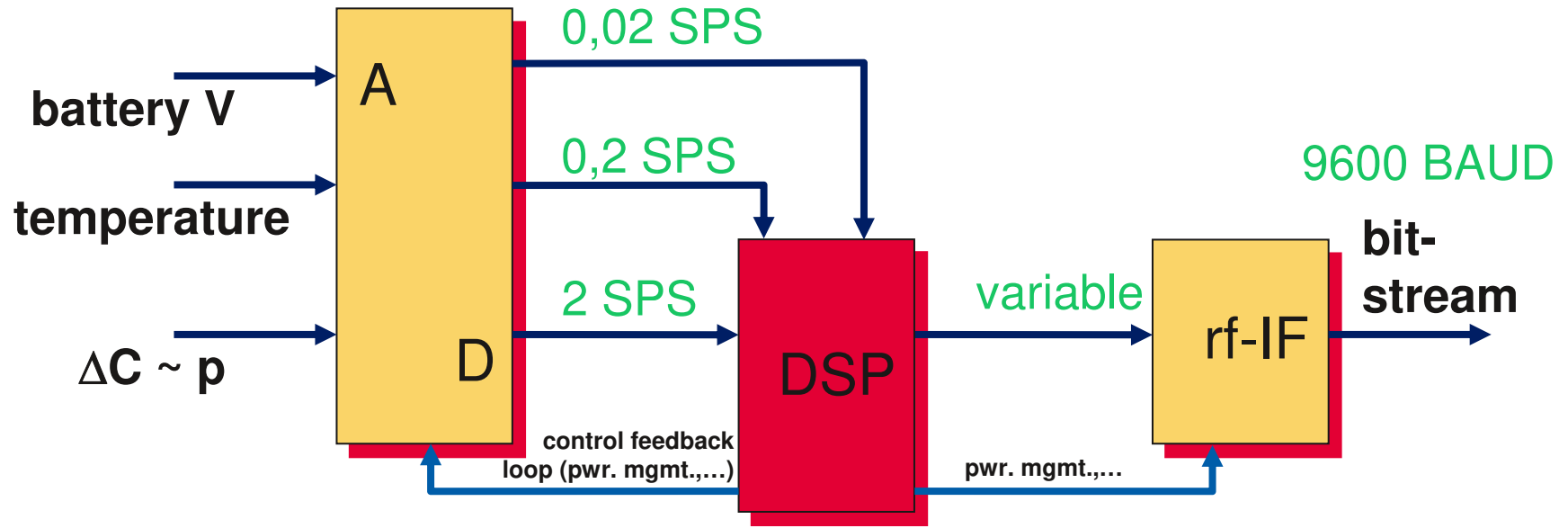
Sensor SoCs require mix of physical, electrical, SDF, TLM and software/algorithm models to one interacting model



The image shows a screenshot of the Eclipse SDK environment. On the left, the Navigator pane shows a project structure with files like 'chopper.sym', 'comparators.xml', and 'dig_int_path.xml'. The main editor displays a C++ source file 'sca_sysc2vhdlf.xml' with comments indicating it is 'M4997 B11 Firmware' and 'version 2, 18.3.2005'. On the right, the qsystem window displays a circuit diagram with various components and connections. The diagram is overlaid with text boxes describing different modeling levels.

DIGITAL EVENT
STATIC DATAFLOW (integer/fp)
TLM
ALGORITHM level only (C)

STATIC DATA FLOW (real domain)
LINEAR ELECTRICAL NETWORKS
NONLINEAR NETWORKS
PHYSICAL MODELS (linear or table based)

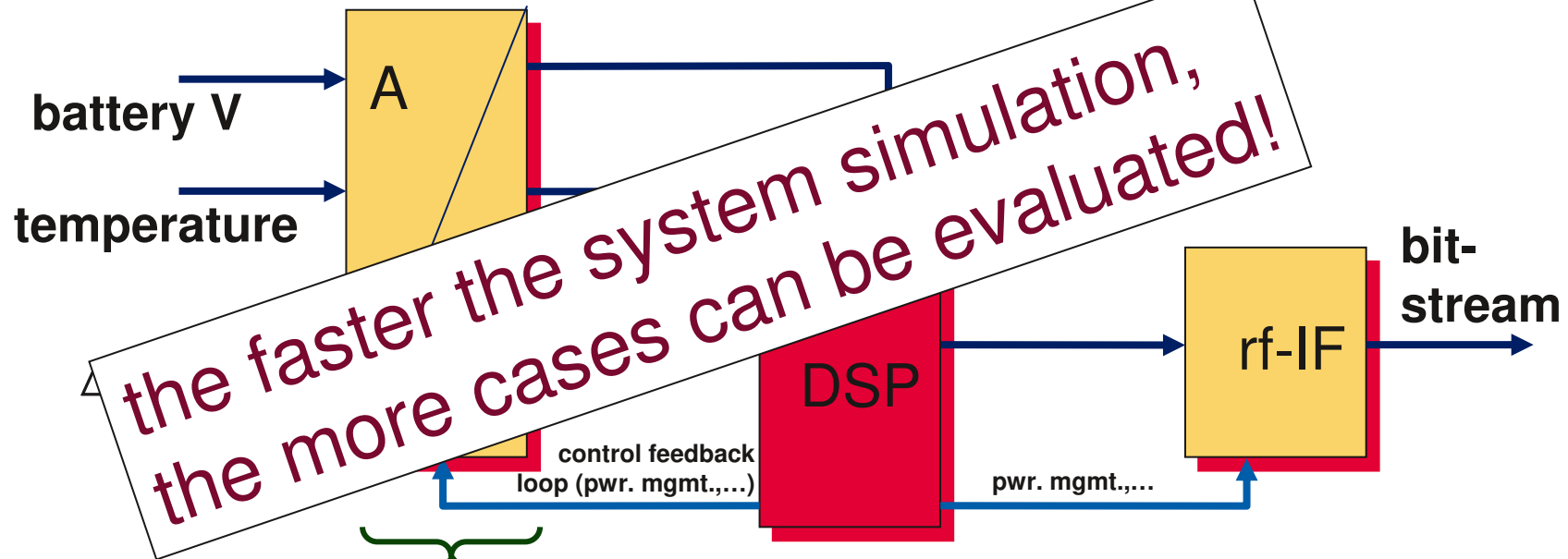


■ Temperature compensated TPMS sensor (MEMS)

- application (driving) $\sim 1/t \sim 250\mu\text{Hz}$ $\left. \begin{array}{l} \text{80} \\ \text{10} \\ \text{10} \\ \text{500000} \end{array} \right\}$
 - battery voltage $\sim 20\text{mHz}$
 - temperature $\sim 200\text{mHz}$
 - pressure (wakeup) $\sim 2\text{Hz}$
 - analog sampling rate $\sim 1\text{MHz}$
 - digital processing rate $\sim 4\text{MHz}$
- speed factor: **$16 \cdot 10^9$**

"transient domain" complexity is high!

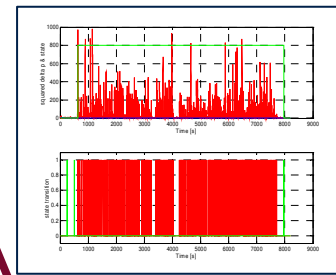
Sensor applications and complexity in time domain shown on an example... 2/2



the faster the system simulation, the more cases can be evaluated!

Simulate one conversion (ADC only)

One parking/driving case to verify data transmission behavior (a "6000 sec." simulation)



- Pure **analog** simulation:
- Pure **VHDL** simulation:
- Abstract **C**-model:

approx. 25 min/conversion "not possible"
approx. 0.1s/conversion "real time"
not noticeable... "minutes range"

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General Requirements



Pressure Sensors



Linear Hall Sensors

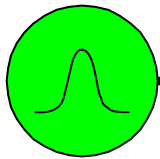
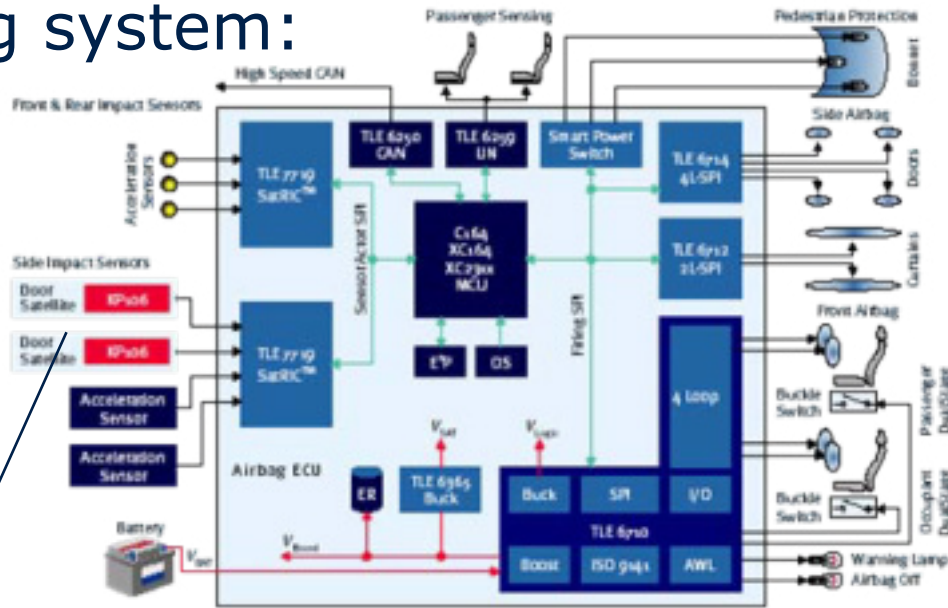


GMR Angle Sensors

Example: Side-Airbag Sensor (pressure based)

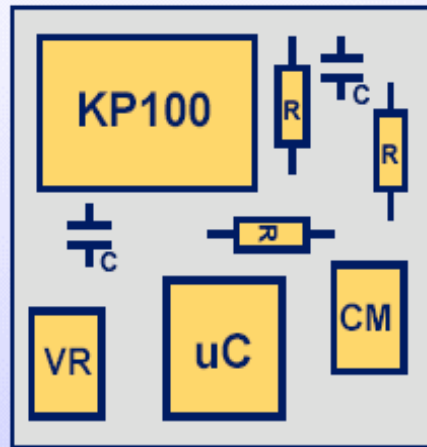
- the evolution steps of a pressure sensor

Airbag system:

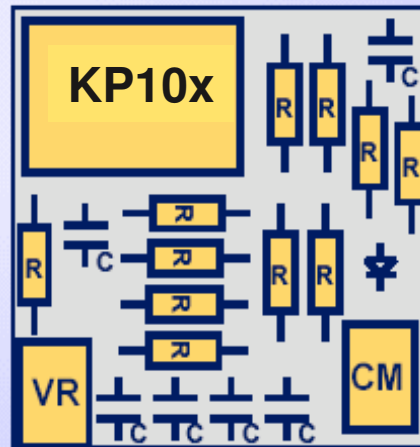


pressure pulse

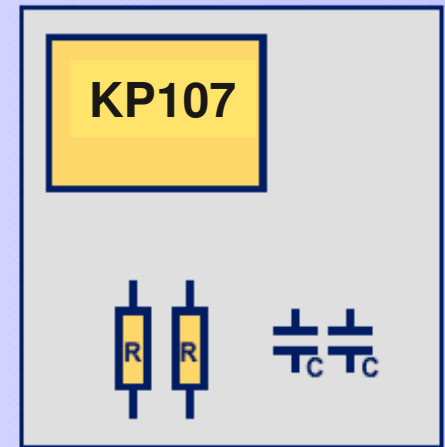
1st generation 1998



2nd generation 2003

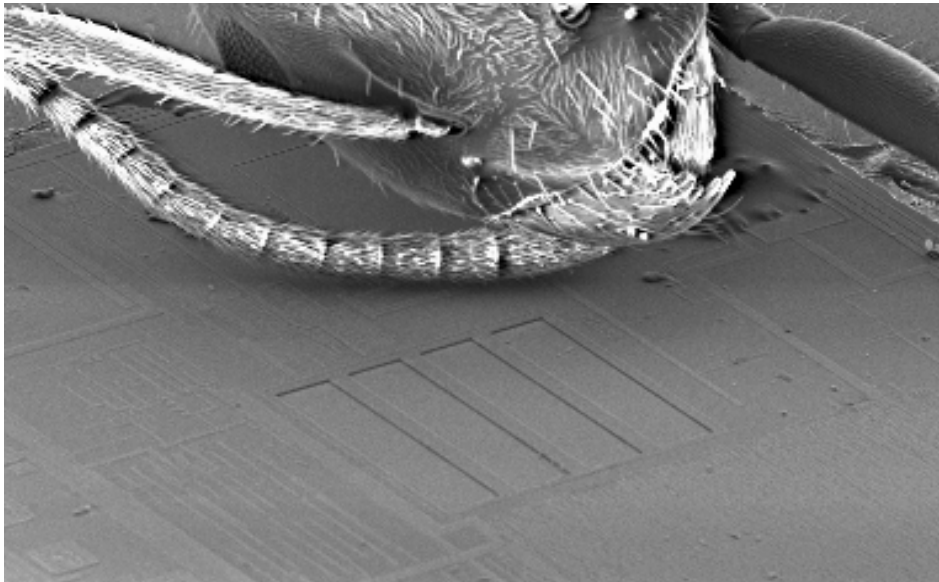


3rd generation 2007



door satellite (PCB)

Sensor Cell Arrangement and Signal Processing

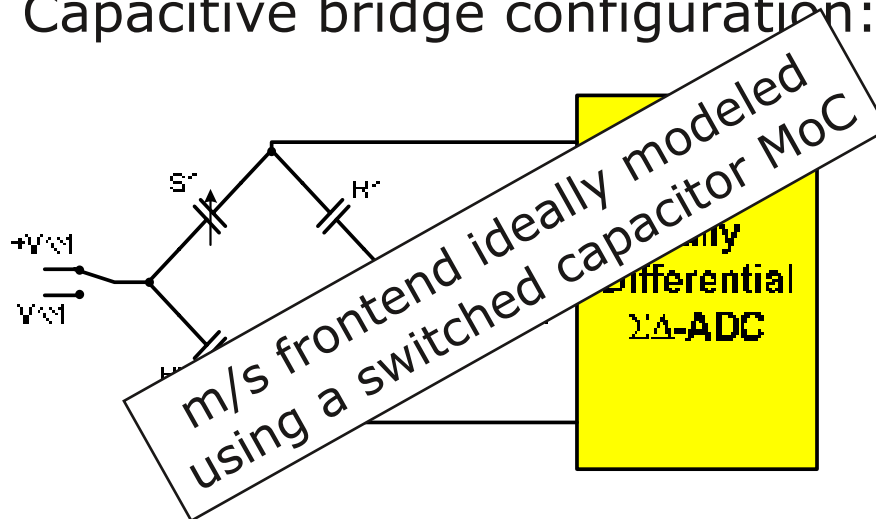


Sensor cells in size comparison with a head of an ant

Effects:

- mismatch effects
- non linearity
- T dependency

Capacitive bridge configuration:



(4 arrays)

$$Q = V_{ref} \cdot [(C_{S1} + C_{S2}) - (C_{R1} + C_{R2})]$$

pressure dependent constant

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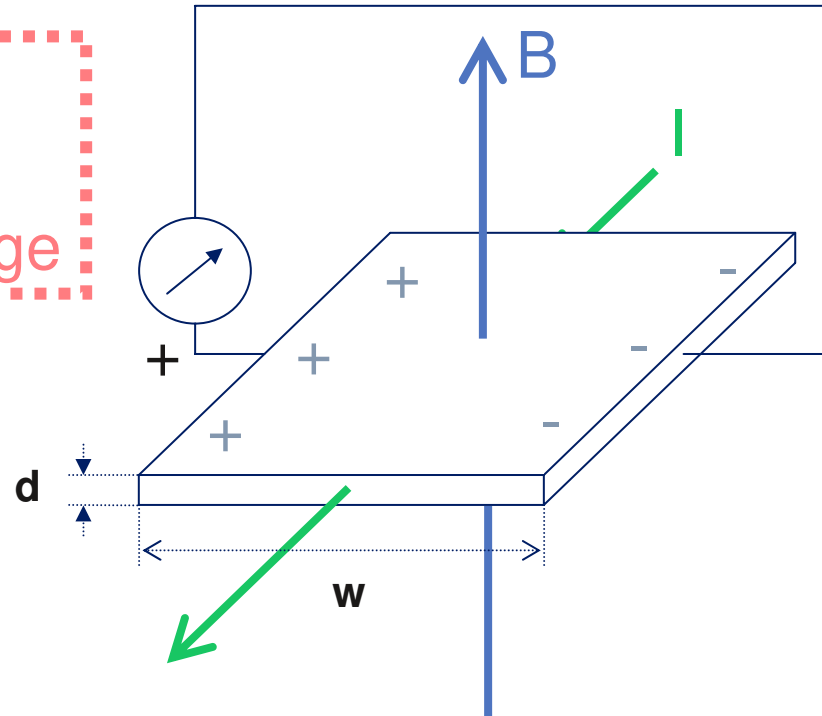
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- **GMR Angle Sensors**

Hall probe modeling

■ modeling and sensor compensation challenges

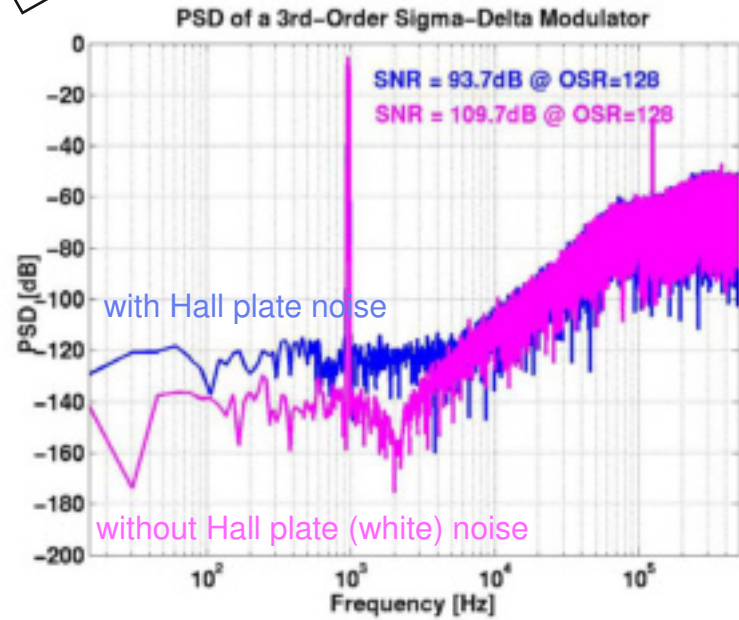
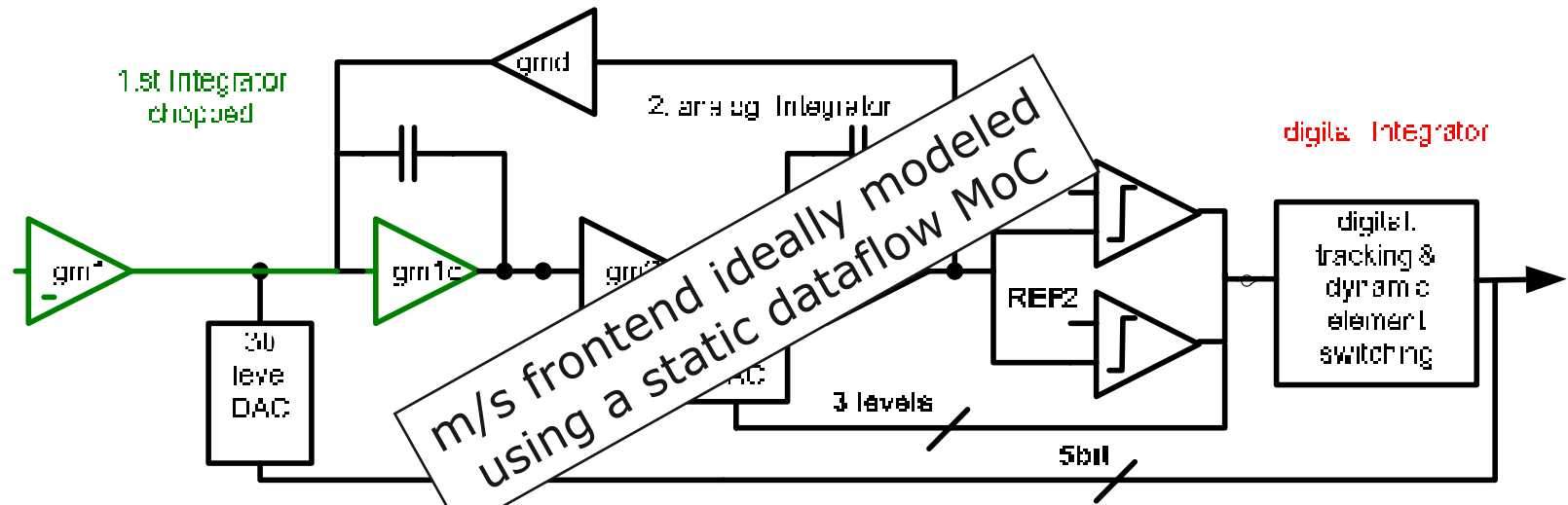
$$V_H = \frac{I B}{n e d}$$

Hall Voltage



- manufacturing tolerances of probe and bias current
- temperature dependency of probe and bias current
- on-chip stress effects, piezoelectric side effects
- noise

Simplified Structure of the Cont.-Time ADC

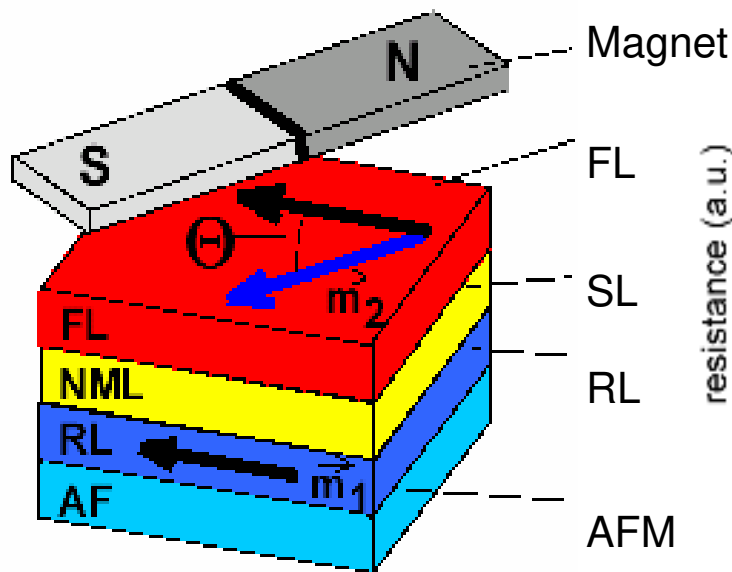
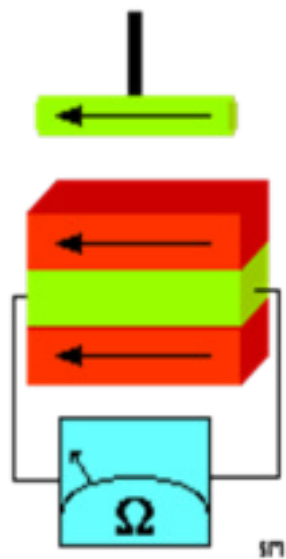


from IEEE sensors paper by M. Motz, et al

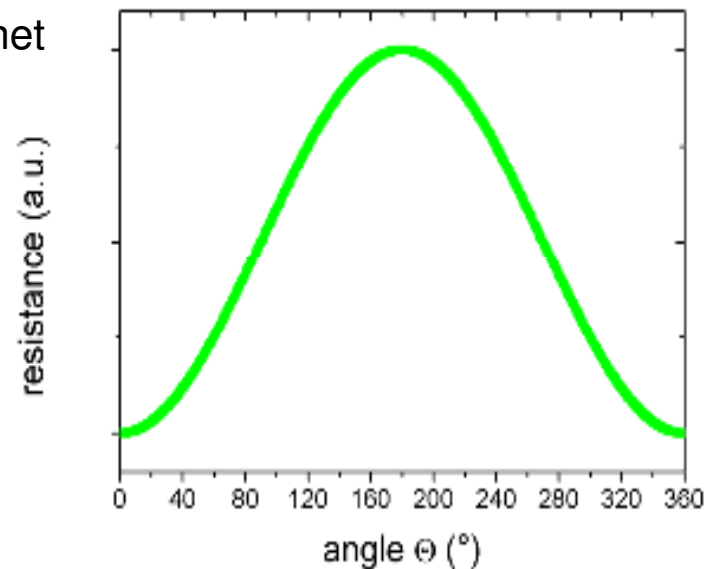
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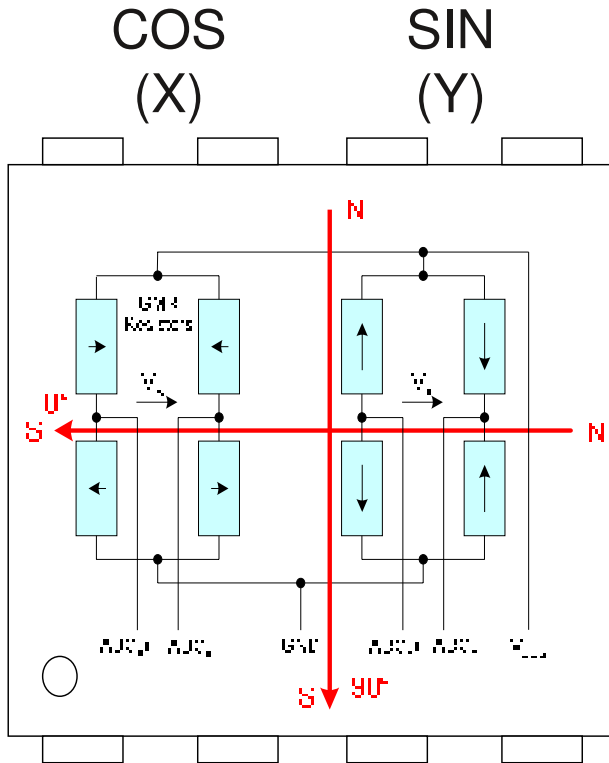
- Effect discovered 1988 (Dr. P. Grünberg)
- The **Resistance** of the spacer layer depends on the external magnetic **Field Direction**



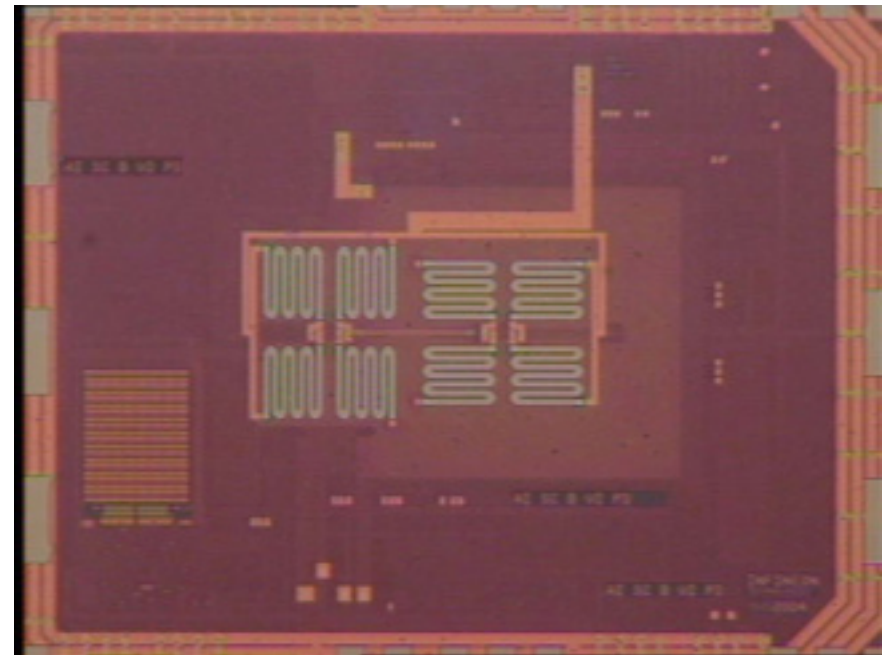
$$\frac{\Delta R}{R}(\Theta_{m1m2}) = \left(\frac{\Delta R}{R}\right)_{GMR} \cdot \frac{(1 - \cos\Theta_{m1m2})}{2}$$



GMR Angle Sensor Basics Sensor Setup



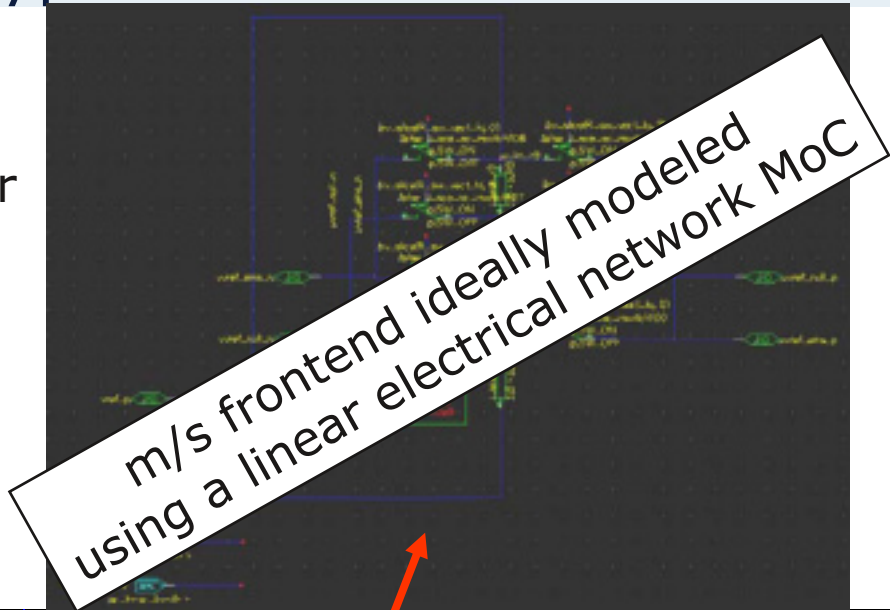
One GMR Wheatstone
Sensor Bridge for each
Orthogonal Direction



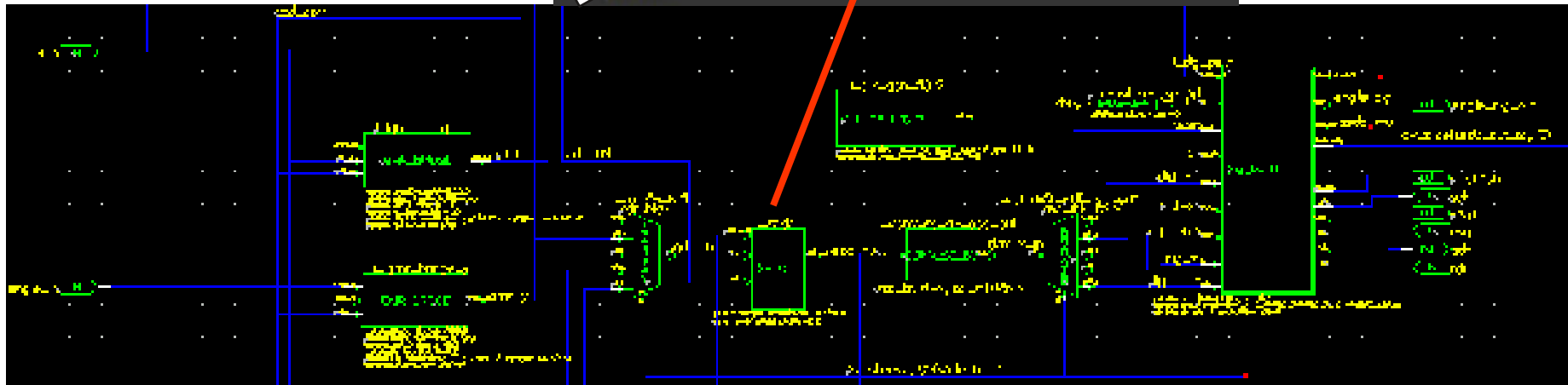
Worldwide First Mass-Productive
Integrated GMR Angle Sensor
(On Top of Active Silicon Area)

GMR Angle Sensor SAR – an example for a typical sensor model

ADC
R-Ladder



Signal Path:



Physical
Input

Sensor
Model

ADC-
Model

DSP
Model



„Never stop thinking“